

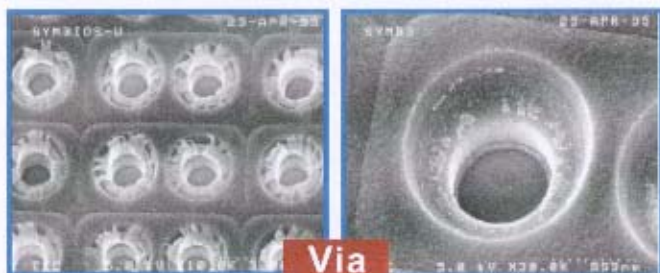


EKC265™

EKC PlasmaSolv® Line - HDA™ Technology

Industry Problems

Incomplete Cleaning by Photoresist REMOVER



Via

EKC265™ is a ready to use semi-aqueous organic mixture formulated to remove etching residues after via, poly and metal etch processes.

Benefits

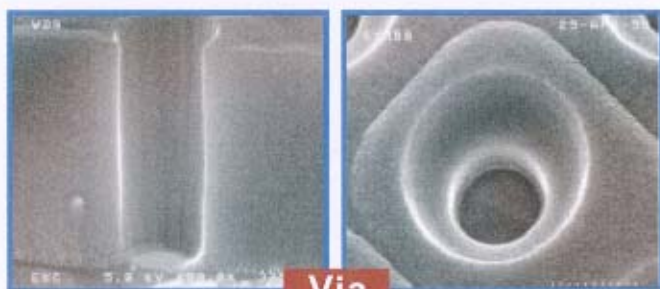
- Improves electrical performance
- Maintains gate oxide integrity
- Improves conductivity between metal layers
- Combines wet chemical processes
- Low rate of evaporation, extends bath life
- Reduces air emissions

Incomplete Cleaning by Photoresist Remover

EKC265™ Clean

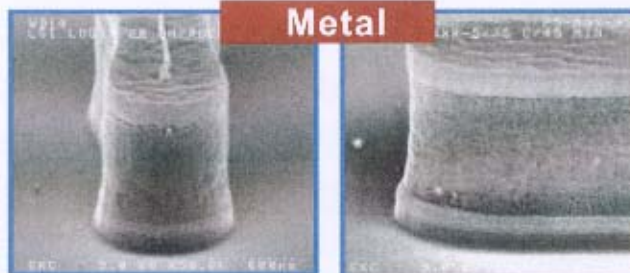
Industry Solution

EKC265™ Clean

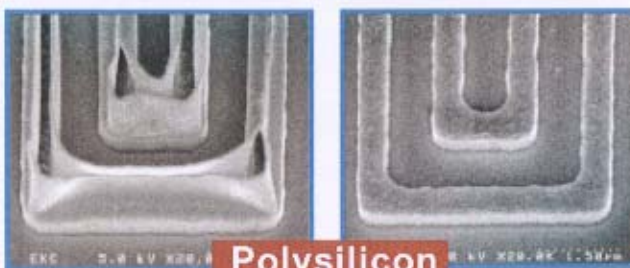


Via

Metal



Polysilicon



EKC265™
U.S. and Foreign
Patents Pending

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EKC Technology

1320 El Capitan Drive, 4th Floor

Danville, CA 94526

tel. +1 (510) 784 9105 facs. +1 (925) 973 1002

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